

江西省晶能半导体有限公司
JiangXi LatticePower Semiconductor Corporation

产 品 规 格 书
Specification

产品名称 Product Name: TK

产品型号 Product P/N: TG-B

客 户 Client name: _____

客户料号 Client P/N: _____

版 本 号 Version No.: A01

日 期 Sending Date: 2022.5.5

客户承认栏 Client Approval	
核准 Approval	确认 Audit

制定 Confirmation: _____ 审核 Approval: _____

工厂地址:江西省南昌市高新区艾溪湖北路 699 号

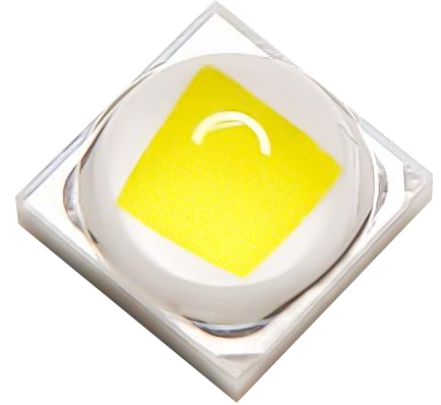
Address: No.699 Aixihu North Road, Nanchang, Jiangxi Province, China

目录 Contents

1、特点 Features.....	1
2、应用 Applications.....	1
3、性能 Performance	2
4、产品代码 Product Order Code	3
5、分档规则 Bin Regulations	7
6、光电特性图 The Photoelectric Characteristics Graph.....	16
7、产品及钢网尺寸 Product and PCB Pad Dimensions.....	13
8、回流焊特性 Reflow Soldering Characteristics	19
9、卷轴 Reel Dimensions.....	20
10、可靠性验证 Reliability.....	21
11、注意事项 Cautions	22

1、特点 Features

- ◆ 陶瓷封装, 高亮度, 高光效
Ceramic Substrate package , High brightness ,High efficiency
- ◆ 尺寸: 3.45mm*3.45mm
Size: 3.45mm*3.45mm
- ◆ 根据 ANSI 标准分档
According to the ANSI standard colour gamut
- ◆ 350mA@85°C分档
Binned at 350mA@85°C
- ◆ 适于 SMT 贴片
Compatible with SMT
- ◆ 发光角度: 120°
Viewing Angle: 120°
- ◆ 包装: 最大 1000 颗/卷
Package: Max: 1000pcs /reel



2、应用 Applications

建筑照明	Architectural
工业照明	Industrial
商业照明	Commercial
室内外照明	Indoor and outdoor area



3、性能 Performance

a) 绝对最大额定值 Absolute Maximum Ratings

参数 Parameter	符号 Symbol	最大参数值 Maximum Rating	单位 Unit
电流 Forward Current	I_F	1500	mA
工作温度 Operating Temperature	T_{opr}	-40~105	°C
存储温度 Storage Temperature	T_{stg}	-40~125	°C
ESD Classification(HBM)		Class 3B(JS-001)	
结温 Junction Temperature	T_j	150	°C

b) 光电参数 Electro-Optical Characteristics (IF=350mA,@85°C)

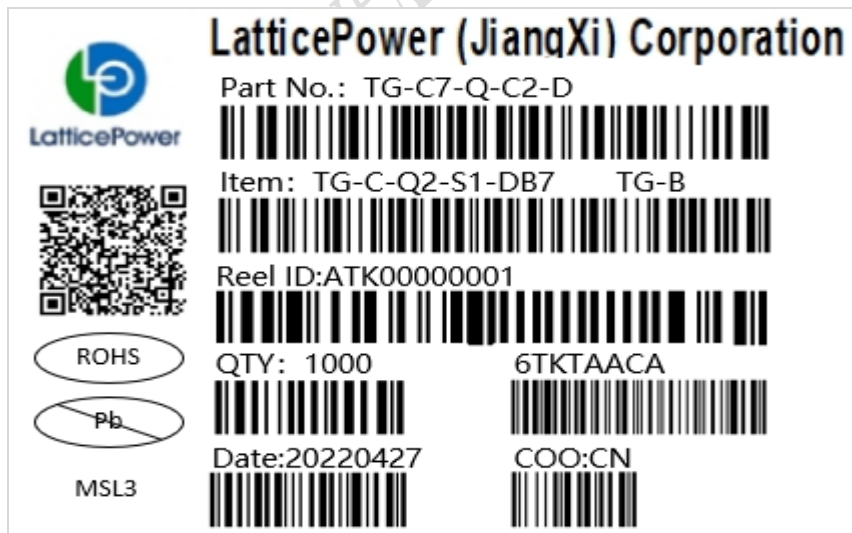
项目 Item	符号 Symbol	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
光通量 Luminous Flux	Φ	Refer to Flux Rank Distribution			Lm
正向电压 Forward Voltage	VF	2.7	2.9	3.1	V
热阻 Thermal Resistance	----	----	6.0	----	°C/W
发光角度 Viewing Angle	2 θ 1/2	----	120	----	°

4、产品代码 Product Order Code

TG - C7 - Q - C2 - D
 ① ② ③ ④ ⑤

- ① 产品型号 Product Type
- ② 显色指数 Ra level
- ③ 色温 CCT
- ④ 亮度 Luminous
- ⑤ 电压 Forward Voltage

a) 出货标签(例) Shipping label (e.g.)



b) Part No.信息 Part No. Information

Digit	PKG Information	Code	Specification				
1	Product	TG	TG				
2	CRI	C7	C	min70			
		75	D	min75			
		C8	E	min80			
		C9	G	min90			
		95	H	min95			
3	CCT(K)	P	6500	1A、1B、1C、1D、P1、P2、P3、P4			
		Q	5700	2A、2B、2C、2D、Q1、Q2、Q3、Q4			
		R	5000	3A、3B、3C、3D、R1、R2、R3、R4			
		T	4000	5A、5B、5C、5D、T1、T2、T3、T4			
		U	3500	6A、6B、6C、6D、U1、U2、U3、U4			
		V	3000	7A、7B、7C、7D、7A3、7B4、7C1、7D2、V1、V2、V3、V4			
		W	2700	8A、8B、8C、8D、W1、W2、W3、W4			
4	Luminous(lm)	A2	150-170	N1,P1	N1	150	160
					P1	160	170
		B2	170-190	Q1,R1	Q1	170	180
					R1	180	190
		C2	190-210	S1,V1	S1	190	200
					V1	200	210
		D2	210-230	W1,Y1	W1	210	220
					Y1	220	230
		E2	190-230	HB,JB	HB	190	210
					JB	210	230
		F2	230-270	KB,MB	KB	230	250
					MB	250	270
		G2	270-310	NB,PB	NB	270	290
					PB	290	310
H2	310-350	QB,RB	QB	310	330		
			RB	330	350		
J2	350-390	SB,TB	SB	350	370		
			TB	370	390		
K2	380-420	U6,V2	U6	380	400		
			V2	400	420		
L2	420-460	V3,V4	V3	420	440		
			V4	440	460		
M2	460-500	V5,V6	V5	460	480		
			V6	480	500		
N2	500-550	V7,V8	V7	500	520		
			V8	520	550		
5	Forward Voltage(V)	D	2.5-3.1	DB6	2.5	2.7	
				DB7	2.7	2.9	
				DB8	2.9	3.1	

c) 亮度分档 Luminous Flux Binning (IF =350mA,@85°C)

Bin	symbol	Min.	Max.	Unit
N1	IV	150	160	lm
P1	IV	160	170	
Q1	IV	170	180	
R1	IV	180	190	
S1	IV	190	200	
V1	IV	200	210	
W1	IV	210	220	

❖ 光通量特性

Luminous Flux Characteristics

CCT	CRI		Condition		Flux
	Typ.@350mA		IF(mA)	Tj(°C)	Typ.
3000	70		350	25	190
			350	85	172
			700	85	319
			1000	85	433
			1200	85	502
4000	70		350	25	200
			350	85	179
			700	85	334
			1000	85	453
			1200	85	526
5000	70		350	25	200
			350	85	180
			700	85	334
			1000	85	452
			1200	85	525

❖ 光通量特性

Luminous Flux Characteristics

CCT	CRI	Condition		Flux
	Typ.@350mA	IF(mA)	Tj(°C)	Typ.
5700	70	350	25	200
		350	85	178
		700	85	333
		1000	85	450
		1200	85	523
6500	70	350	25	190
		350	85	172
		700	85	318
		1000	85	430
		1200	85	499

备注 Notes :

❖ 光通量测量误差范围±7%

Luminous flux measurement tolerance: ±7%

d) 电压分档 Forward Voltage Binning (IF =350mA,@85°C)

Bin	symbol	Min.	Max.	Unit
DB6	VF	2.5	2.7	V
DB7	VF	2.7	2.9	
DB8	VF	2.9	3.1	

备注 Notes :

- ◇ 电压测量误差范围±0.06V
Tolerance is ±0.06V on voltage measurements

e) 显指分档 Ra Groups (IF =350mA,@85°C)

Bin	symbol	Min.	Max.	R9
C	CRI	70	80	/
E	CRI	80	90	Min.0
G	CRI	90	100	Min.50
H	CRI	95	100	Min.75

备注 Notes :

- ◇ 显指测量误差范围±2
Tolerance is ±2 on CRI measurements

f) 亮度分布 Flux Rank Distribution (IF =350mA,@85°C)

CRI 70

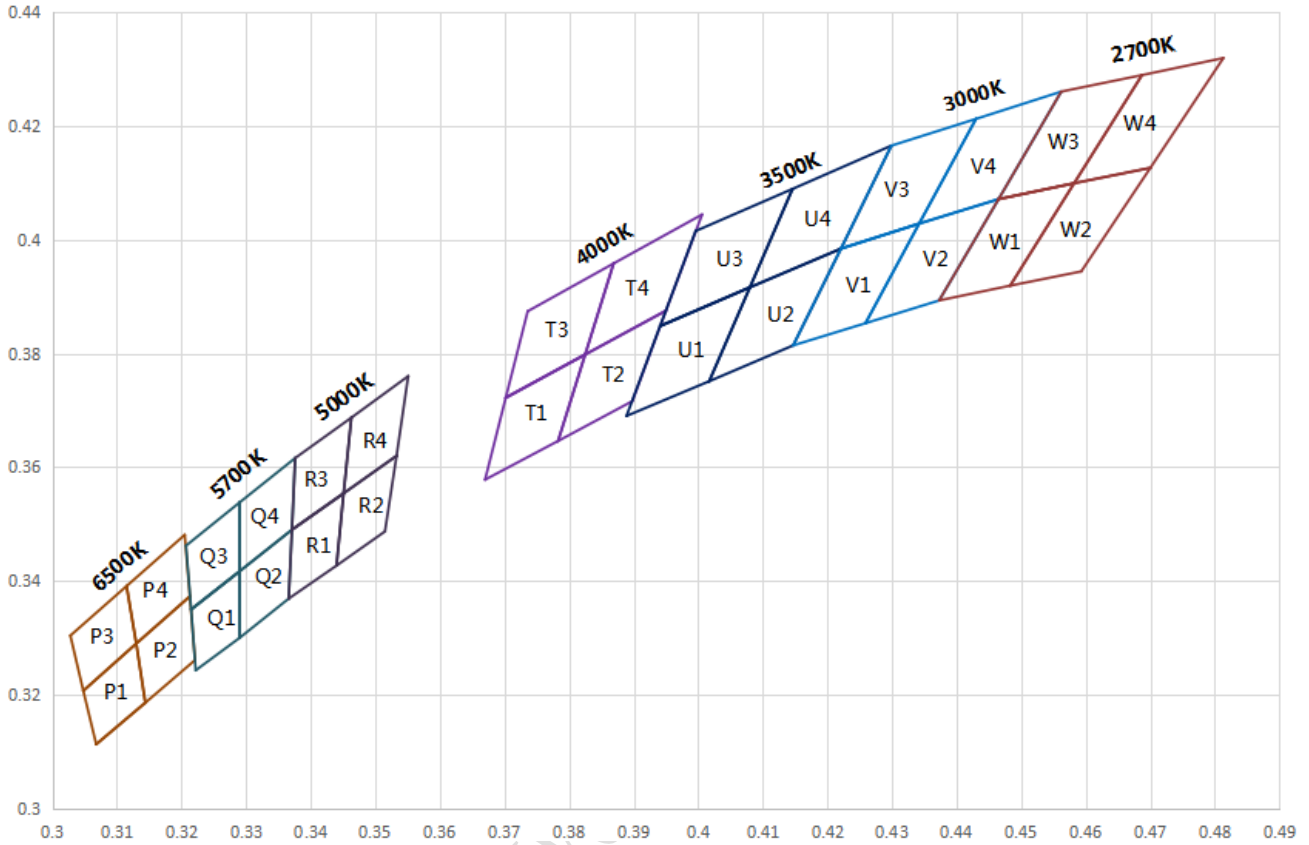
■ 供货等级 Available Rank

CCT	CIE	CRI	Flux Rank						
3000	7	70	N1	P1	Q1	R1	S1	V1	W1
4000	5	70	N1	P1	Q1	R1	S1	V1	W1
5000	3	70	N1	P1	Q1	R1	S1	V1	W1
5700	2	70	N1	P1	Q1	R1	S1	V1	W1
6500	1	70	N1	P1	Q1	R1	S1	V1	W1

LatticePower Semiconductor

5、色区分档规则 Color Bin Regulations (IF =350mA, @85°C)

a) 色区图 CIE Chromaticity Diagram



b) ANSI Bin 定义 ANSI Color bin definitions

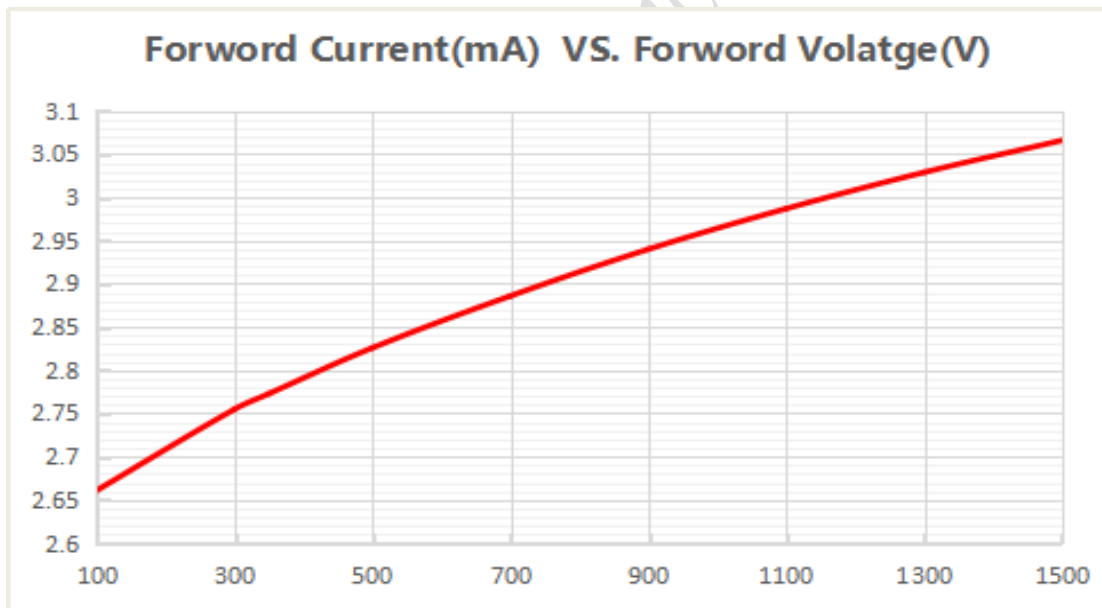
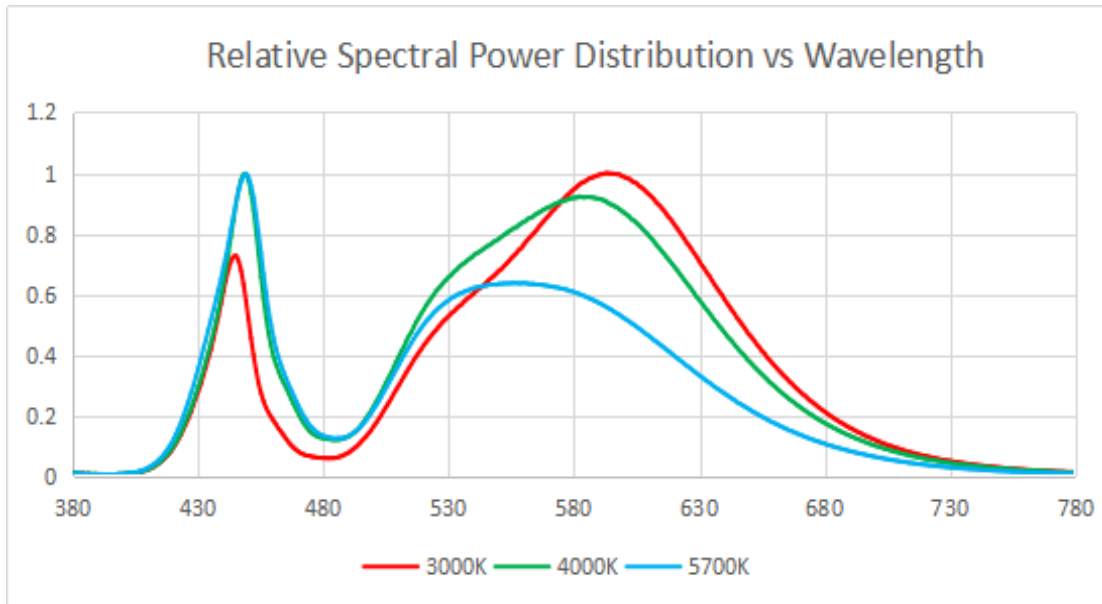
色区	X	Y	色区	X	Y	色区	X	Y	色区	X	Y
P1	0.3068	0.3113	P2	0.3144	0.3186	P3	0.3048	0.3207	P4	0.3130	0.3290
	0.3144	0.3186		0.3221	0.3261		0.3130	0.3290		0.3213	0.3373
	0.3130	0.3290		0.3213	0.3373		0.3115	0.3391		0.3205	0.3481
	0.3048	0.3207		0.313	0.329		0.3028	0.3304		0.3115	0.3391
Q1	0.3215	0.3350	Q2	0.3290	0.3417	Q3	0.3207	0.3462	Q4	0.3290	0.3538
	0.329	0.3417		0.3371	0.349		0.329	0.3538		0.3376	0.3616
	0.329	0.33		0.3366	0.3369		0.329	0.3417		0.3371	0.349
	0.3222	0.3243		0.3290	0.3300		0.3215	0.3350		0.3290	0.3417
R1	0.3371	0.3490	R2	0.3451	0.3554	R3	0.3376	0.3616	R4	0.3463	0.3687
	0.3451	0.3554		0.3533	0.362		0.3463	0.3687		0.3551	0.376
	0.344	0.3427		0.3515	0.3487		0.3451	0.3554		0.3533	0.362
	0.3366	0.3369		0.3440	0.3427		0.3371	0.3490		0.3451	0.3554

色区	X	Y	色区	X	Y	色区	X	Y	色区	X	Y
T1	0.3702	0.3722	T2	0.3825	0.3798	T3	0.3736	0.3874	T4	0.3869	0.3958
	0.3825	0.3798		0.3950	0.3875		0.3869	0.3958		0.4006	0.4044
	0.3783	0.3646		0.3898	0.3716		0.3825	0.3798		0.3950	0.3875
	0.367	0.3578		0.3783	0.3646		0.3702	0.3722		0.3825	0.3798
U1	0.3941	0.3848	U2	0.408	0.3916	U3	0.3996	0.4015	U4	0.4146	0.4089
	0.4080	0.3916		0.4221	0.3984		0.4146	0.4089		0.4299	0.4165
	0.4017	0.3751		0.4147	0.3814		0.4080	0.3916		0.4221	0.3984
	0.3889	0.369		0.4017	0.3751		0.3941	0.3848		0.4080	0.3916
V1	0.4221	0.3984	V2	0.4342	0.4028	V3	0.4299	0.4165	V4	0.4430	0.4212
	0.4342	0.4028		0.4465	0.4071		0.443	0.4212		0.4562	0.426
	0.4259	0.3853		0.4373	0.3893		0.4342	0.4028		0.4465	0.4071
	0.4147	0.3814		0.4259	0.3853		0.4221	0.3984		0.4342	0.4028
W1	0.4465	0.4071	W2	0.4582	0.4099	W3	0.4562	0.426	W4	0.4687	0.4289
	0.4582	0.4099		0.4700	0.4126		0.4687	0.4289		0.4813	0.4319
	0.4483	0.3919		0.4593	0.3944		0.4582	0.4099		0.4700	0.4126
	0.4373	0.3893		0.4483	0.3919		0.4465	0.4071		0.4582	0.4099

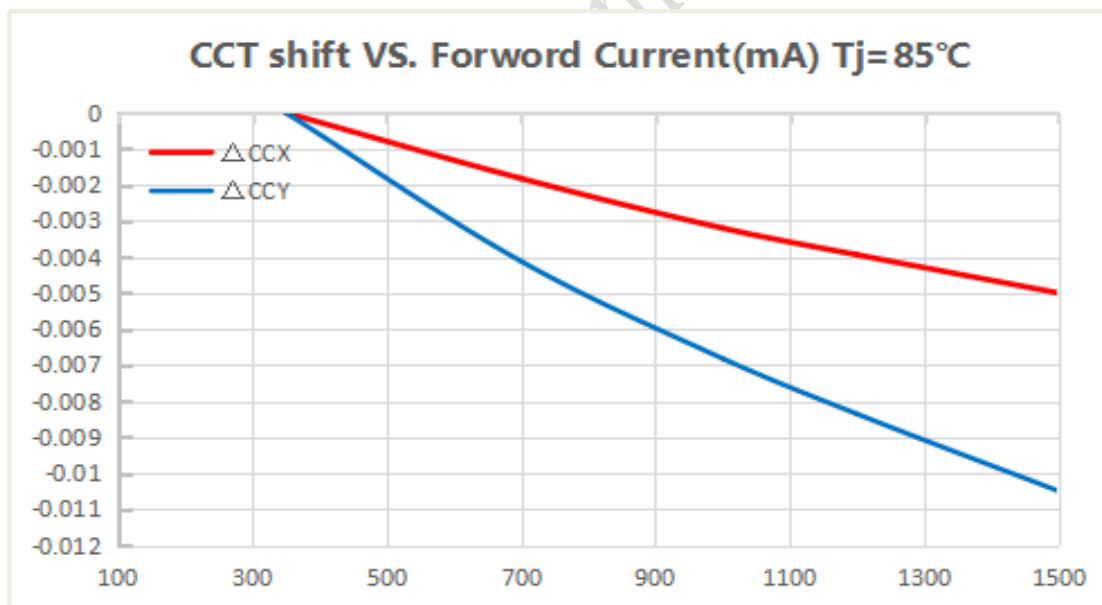
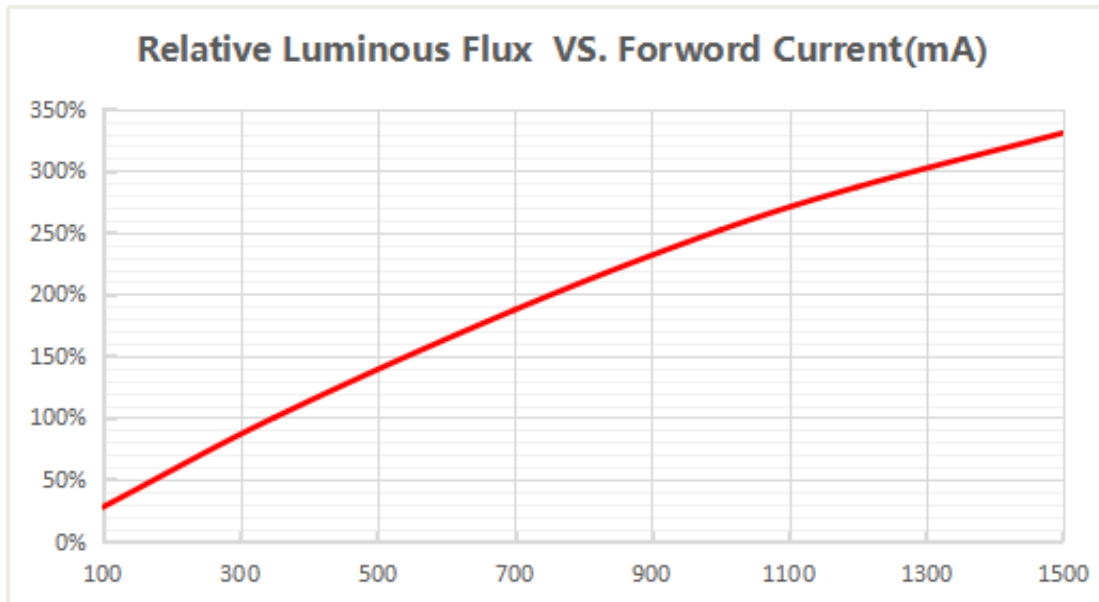
备注 Notes :

- ◇ 色度坐标 (x, y) 来自 CIE1931 色度图
The chromaticity coordinates(x,y)is derived from the CIE 1931 chromaticity diagram
- ◇ 测试分选设备用于光通量 (lm) 和 CIE1931 色度坐标 (x, y) 测试。
Testing & Sorting Machine is for the luminous flux(lm) and the CIE1931 chromaticity coordinates(x,y) testing.
- ◇ 色度坐标 (x, y) 存在±0.006 公差。
The chromaticity coordinates(x,y) guarantee should be added ±0.006 tolerance.

6、光电特性图 The Photoelectric Characteristics Graph

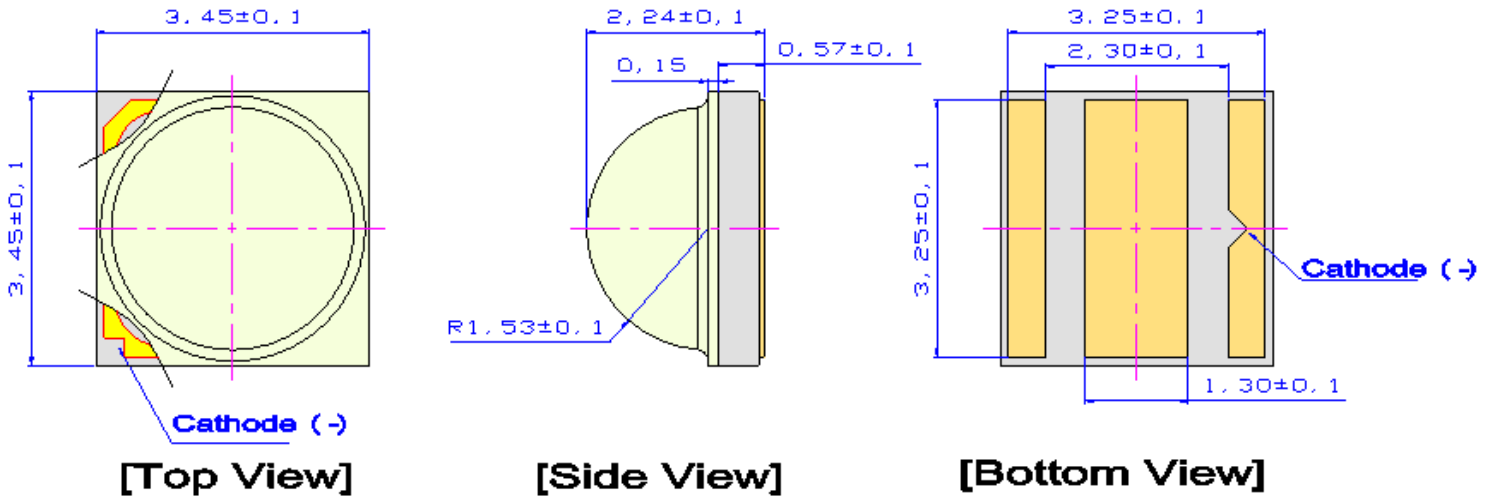


7、光电特性图 The Photoelectric Characteristics Graph

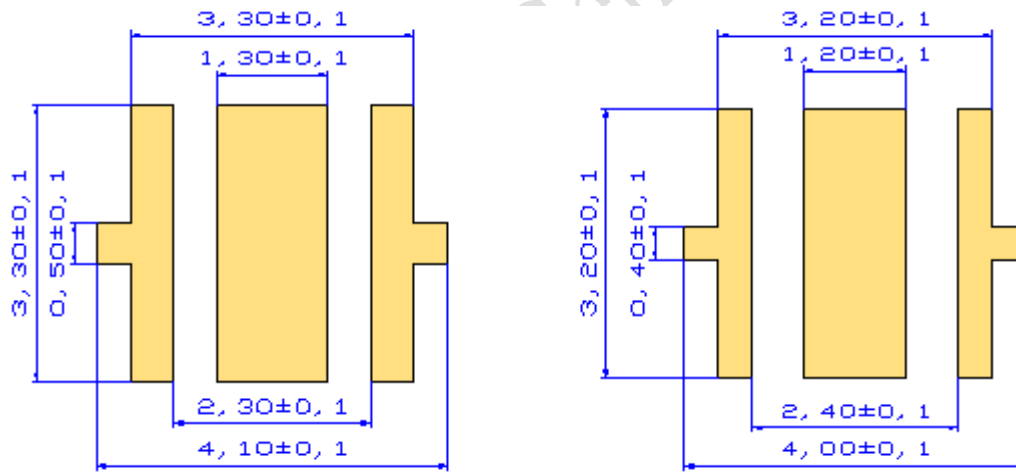


8、产品及钢网尺寸 Product and PCB Pad Dimensions

Product Dimensions:



PCB Pad Dimensions:



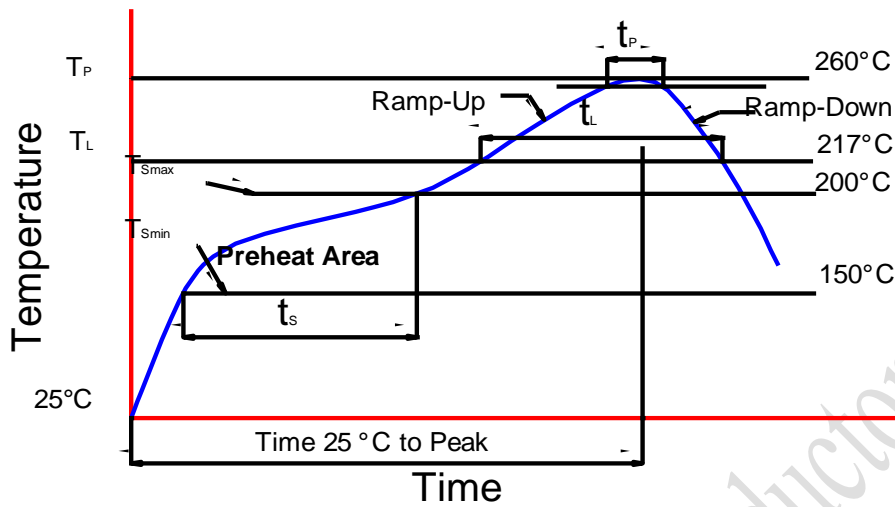
建议 PCB 焊盘

建议钢网

备注 Notes:

- ◇ 所有尺寸均以 mm 为单位
All dimensions are in millimeters
- ◇ 尺寸公差: ± 0.1 mm
Dimension tolerance: ± 0.1 mm

9、回流焊特性 Reflow Soldering Characteristics

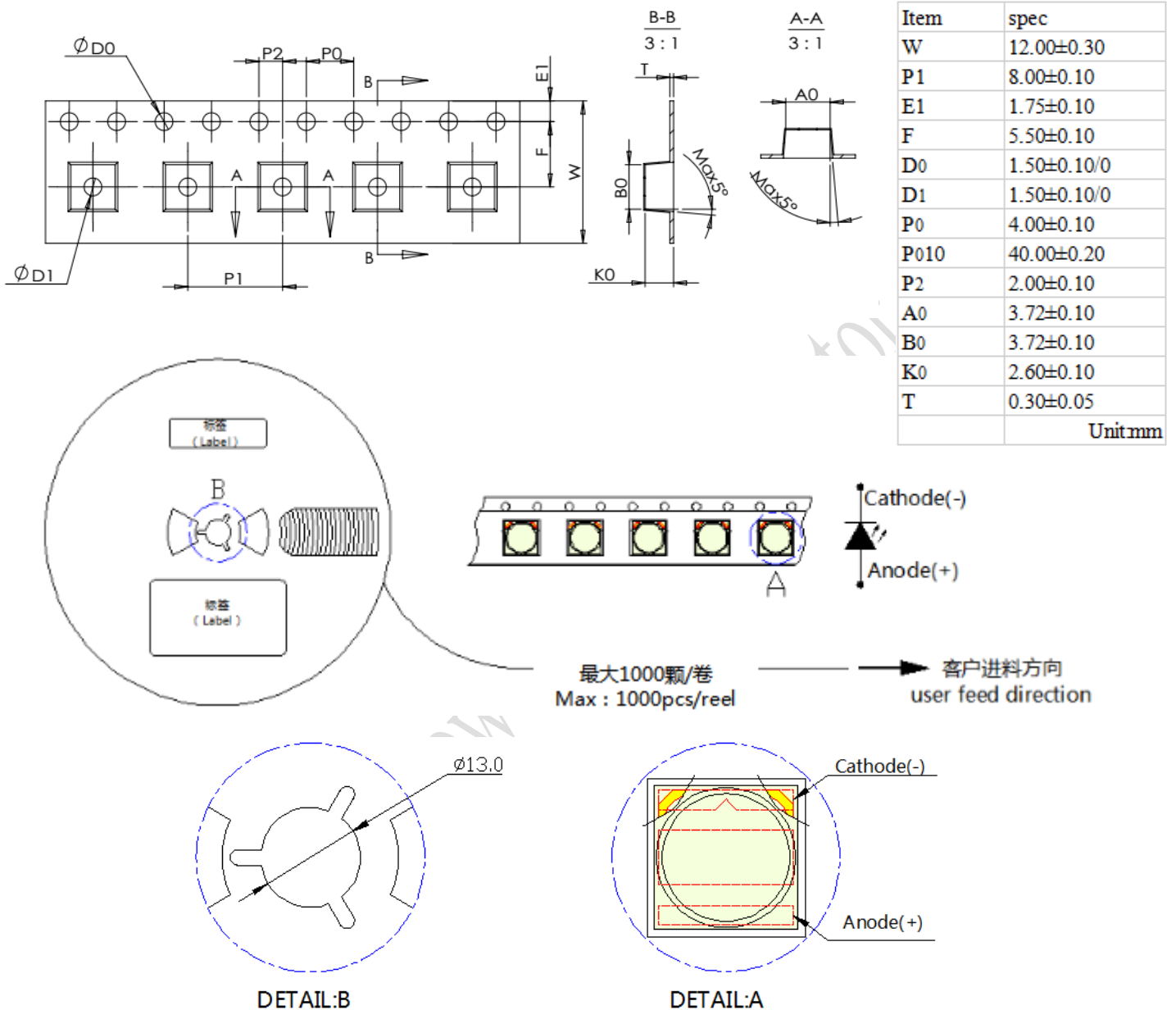


根据 EDEC-J-STD-020D 内容, 参考以下内容。

Compatible with the JEDEC-J-STD-020D, using the parameters listed below.

特制参数 Profile Feature	无铅焊料 Lead-Free Solder
平均上升速率 (Tsmax 至 Tp) Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec max.
预热: 温度最小值 (Tsmin) Preheat: Temperature Min (Tsmin)	150
预热: 最高温度 (Tsmax) Preheat: Temperature Max (Tsmax)	200
预热: 时间 (tsmin 到 tsmax) Preheat: Time (tsmin to tsmax)	60-180 secs
回流温度 (TL) Time Maintained Above: Temperature (TL)	217°C
回流时间 (tL) Time Maintained Above: Time (tL)	60-150 secs
峰值/分类温度 (Tp) Peak/Classification Temperature(Tp)	255±5°C
实际峰值温度 (tp) 在 5°C 以内的时间 Time Within 5°C of Actual Peak Temperature (tp)	20~40 secs
降低速率 Ramp-Down Rate	5°C/sec max.

10、 卷轴 Reel Dimensions



备注 Notes:

- ◇ 卷轴包装 1000pcs
Reel:1000pcs.
- ◇ 卷轴包装方法符合 IJSC0806 (连续胶带上的电子元件包装)
The tape packing method complies with IJSC0806(Packing of Electronic Components on Continuous Tapes.
- ◇ 当卷轴由于工作中断而重绕时, 载带上压力不应超过 10N, 否则 LED 可能会粘在盖带上
When the tape is rewound due to work interruptions, no more than 10N should be applied to the embossed carrier tape.
The LEDs may stick to the cover tape.

11、可靠性 Reliability

a) 测试和结果 Tests and Results

测试项目 Test Item	参考标准 Reference Standard	测试条件 Test Conditions	测试周期 Test Duration	失效标准 Failure Criteria#	失效数/测试数 Units Failed/Tested
可焊性 (回流焊) Solderability(Reflow Soldering)	JEITA ED=4701 303 303A	$T_{sld}=255\pm 5^{\circ}\text{C}$,5sec,Lead-free Solder(Sn-3.0Ag-0.5Cu)	3times	#2	0/22
高低温循环 Temperature Cycle	JEITA ED=4701 100 105	-40°C (30min) $\sim 25^{\circ}\text{C}$ (5min) $\sim 85^{\circ}\text{C}$ (30min) $\sim 25^{\circ}\text{C}$ (5min)	100cycles	#1	0/22
高温/低温储存 High/Low Temperature Storage	JEITA ED=4701 200 201/ JEITA ED=4701 200 202	$T_A=120^{\circ}\text{C}/T_A=-40^{\circ}\text{C}$	1000h	#1	0/22
常温老化 Room Temperature Operating		$T_A=25^{\circ}\text{C}$, $I_F=1200\text{mA}$	1000h	#1	0/22
高温老化 High Temperature Operating		$T_A=85^{\circ}\text{C}$, $I_F=1200\text{mA}$	1000h	#1	0/22
高温高湿老化 Temperature Humidity Operating		85°C , RH=85%, $I_F=1200\text{mA}$	1000h	#1	0/22

b) 失效判定 Failure Criteria

判定 Criteria #	项目 Items	条件 Conditions	失效判定 Failure Criteria
#1	正向电压 Forward Voltage (VF)	I_F	$> \text{初始值} \times 1.1 \text{ 倍}$ $> \text{Initial value} \times 1.1$
	光通量 Luminous Flux (Φ_v)	I_F	$< \text{初始值} \times 0.7 \text{ 倍}$ $< \text{Initial value} \times 0.7$
	反向电流 Reverse Current (IR)	$V_R=5\text{V}$	$> 1\mu\text{A}$ $> 1\mu\text{A}$
#2	回流焊 Solderability	-	焊接面积 $< 80\%$ Less than 80% solder coverage

12、注意事项 Cautions

a) 操作注意 Handling Precautions



1) LED 上的压力会影响 led 的可靠性。应采取预防措施，以避免对 led 的强压力。在加热过程中不要对 led 施加压力。

Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.

2) LED 焊接完毕后不应重新焊接。如果重新焊接不可避免，那么在修复之前和修复之后都要仔细检查 LED 的特性。

Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.

3) 不要将组装好的 pcb 堆在一起。由于 LED 的材料是软的，与 LED 组装的两个 PCB 之间的磨损可能会导致 LED 破坏性的故障。

Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

4) 与标准的封装材料相比，硅胶通常更柔软，表面更容易吸引灰尘，如果不能保证最低程度的灰尘和灰尘颗粒，在部件焊接后，必须在表面使用合适的清洗液。

Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components.

5) 灯具材料中释放的挥发性有机化合物(VOCs)可以穿透 LED 的硅树脂封装，暴露在热量和光子能量下会变色。结果可能是灯具的光输出有重大损失。

VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LED and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture.

6) 安装 led 时，不要使用释放有机蒸汽的粘合剂。

Attaching LEDs, do not use adhesives that outgas organic vapor..

7) LED 对 ESD (Electro-Static Discharge, ESD)敏感。以下是晶能半导体公司为减少这些影响而提出的一些建议。

LED is sensitive to Electro-Static Discharge (ESD). Below is a list of suggestions that LatticePower Semiconductor purposes to minimize these effects.

a. ESD(静电放电)

静电放电(ESD)定义为两个物体接触时释放出的静电。虽然大多数 ESD 事件被认为是无害的,但在许多工业环境中,在生产和存储期间,它可能是一个代价比较大的问题。ESD 对 LED 的损害可能导致产品显示出不同寻常的特性,例如:一反向泄漏电流的增加降低了开启电压

ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is the defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LED may cause the product to demonstrate unusual characteristics such as: - Increase in reverse leakage current lowered turn-on voltage.

-LED 在低电流时发射异常 Abnormal emissions from the LED at low current

以下建议可以帮助减少 ESD 发生的可能性。

The following recommendations are suggested to help minimize the potential for an ESD event.

一个或多个工作区域建议:

One or more work area suggestions:

-电离风扇设置 Ionizing fan setup

-导电材料制成的防静电台面/搁板垫 ESD table/shelf mat made of conductive materials

-防静电安全容器 ESD safe storage containers

一个或多个人员建议选择::

One or more personnel suggestion options:

-防静电腕带 Antistatic wrist-strap

-防静电材料鞋 Antistatic material shoes

-防静电衣服 Antistatic clothes

环境控制:

Environmental controls:

-湿度控制(干燥环境下防静电效果较差) Humidity control (ESD gets worse in a dry environment)

b) 清洗 Cleaning

1) 建议使用异丙醇进行清洗。如果使用其他溶剂，必须保证这些溶剂不溶解包装或树脂。不建议使用超声波清洗。超声波清洗可能会对 LED 造成损坏。

We suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

c) 存储 Storage

➤ 不要将 LED 放在潮湿的地方，存放温度在 5°C~30°C 之间，相对湿度在 30% 以下。
Do not place the LED in damp places, Storage temperature between 5 °C and 30 °C, Relative humidity under 30%.

➤ 打开包装后使用注意事项 Use Precaution after Opening the Packaging

a) 开包后推荐条件 Recommend conditions after opening the package

-密封/温度：5~30°C 湿度：小于 60%

- Sealing / Temperature : 5 ~ 30°C Humidity : less than RH60%

b) 如果包装已打开超过 168H(MSL 3)或湿度指示卡颜色发生变化，应在 65±5°C 条件下干燥 10-24H

If the package has been opened more than 168 hours (MSL 3) or the color of the Humidity indicator card changes, components should be dried for 10-24hr at 65±5°C

13、 文件履历表 Document Resume

序号	变更日期	变更人	版本	变更内容
1	2021.9.1	王宝	A00	新版发行
2	2022.5.5	王宝	A01	修改标签模板，新增 Part No.信息
3				
4				
5				

LatticePower Semiconductor